

## EAST Search History

## EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	8	"6413850"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2012/02/10 17:47
L2	288	solder NEAR10 spin NEAR3 coat\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2012/02/10 17:47
S2	299	((isao ADJ sakamoto) OR (sakamoto ADJ isao) OR (junichi ADJ onozaki) OR (onozaki ADJ junichi) OR (masahiko ADJ furuno) OR (furuno ADJ masahiko) OR (hiroshi ADJ saito) OR (saito ADJ hiroshi) OR (haruhiko ADJ ando) OR (ando ADJ haruhiko) OR (masaru ADJ shira) OR (shirai ADJ masaru) OR (atsushi ADJ hiratuka) OR (hiratuka ADJ atsushi)).in.	US-PGPUB; USPAT	OR	ON	2008/06/26 17:35
S4	300	148/25.ccls.	US-PGPUB; USPAT	OR	ON	2008/06/26 17:40
S5	30597	solder AND bump	US-PGPUB; USPAT	OR	ON	2008/06/30 09:05
S6	5259	solder AND bump AND flux	US-PGPUB; USPAT	OR	ON	2008/06/30 09:06
S7	146	solder AND bump AND flux AND acid AND fat\$2	US-PGPUB; USPAT	OR	ON	2008/06/30 09:07
S8	0	solder AND bump AND flux AND acid AND fat\$2 AND neopentylpolyester	US-PGPUB; USPAT	OR	ON	2008/06/30 09:07
S9	0	solder AND bump AND flux AND acid AND fat\$2 AND neopentylpolyoester	US-PGPUB; USPAT	OR	ON	2008/06/30 09:08
S11	11	solder AND bump AND flux AND acid AND fat\$2 ADJ ester	US-PGPUB; USPAT	OR	ON	2008/06/30 09:08
S12	0	("2003/0176599").URPN.	USPAT	OR	ON	2008/06/30 09:09
S13	3	solder AND bump AND flux AND acid AND fat\$2 AND (solder ADJ (diameter OR size))	US-PGPUB; USPAT	OR	ON	2008/06/30 09:24
S14	3	solder AND bump AND flux AND acid AND fat\$2 AND (solder ADJ (diameter OR radius OR size))	US-PGPUB; USPAT	OR	ON	2008/06/30 09:25
S15	13439	solder AND flux AND (organic ADJ acid OR flux OR free ADJ fatty ADJ acid OR neopentylpolyol ADJ ester) AND (fat OR	US-PGPUB; USPAT	OR	ON	2008/06/30 14:37

		fatty ADJ acid ADJ ester) fatty ADJ oil				
S16	13003	solder AND bump AND flux AND (organic ADJ acid OR flux OR free ADJ fatty ADJ acid OR neopentylpolyol ADJ ester) AND (fat OR fatty ADJ acid ADJ ester) fatty ADJ oil	US-PGPUB; USPAT	OR	ON	2008/06/30 14:37
S18	341	solder AND bump AND flux AND (neopentylpolyol ADJ ester) AND (fat OR fatty ADJ acid ADJ ester) fatty ADJ oil AND (tin OR sn) AND (silver OR ag) AND (copper OR cu)	US-PGPUB; USPAT	OR	ON	2008/06/30 14:39
S19	2	solder AND bump AND flux AND (neopentylpolyol ADJ ester) AND (fat OR fatty ADJ acid ADJ ester) AND fatty ADJ oil AND (tin OR sn) AND (silver OR ag) AND (copper OR cu)	US-PGPUB; USPAT	OR	ON	2008/06/30 14:42
S20	2	solder AND bump AND flux AND (organic ADJ acid OR flux OR free ADJ fatty ADJ acid OR neopentylpolyol ADJ ester) AND (fat OR fatty ADJ acid ADJ ester) fatty ADJ oil AND (tin OR sn) AND (silver OR ag) AND (copper OR cu)	US-PGPUB; USPAT; EPO; JPO; DERWENT	AND	ON	2008/06/30 14:43
S21	2	solder AND bump AND flux AND (organic ADJ acid OR flux OR free ADJ fatty ADJ acid OR neopentylpolyol ADJ ester) AND (fat OR fatty ADJ acid ADJ ester) fatty ADJ oil	US-PGPUB; USPAT; EPO; JPO; DERWENT	AND	ON	2008/06/30 14:44
S22	7	solder AND flux AND (organic ADJ acid OR flux OR free ADJ fatty ADJ acid OR neopentylpolyol ADJ ester) AND (fat OR fatty ADJ acid ADJ ester) fatty ADJ oil	US-PGPUB; USPAT; EPO; JPO; DERWENT	AND	ON	2008/06/30 14:44
S23	566	solder AND flux AND (organic ADJ acid OR flux OR free ADJ fatty ADJ acid OR neopentylpolyol ADJ ester) AND (fat OR fatty ADJ acid ADJ ester)	US-PGPUB; USPAT; EPO; JPO; DERWENT	AND	ON	2008/06/30 15:01
S24	372	solder AND (particle OR precipitate) AND flux AND (organic ADJ acid OR flux OR free ADJ fatty ADJ acid OR neopentylpolyol ADJ ester) AND (fat OR fatty ADJ acid ADJ ester)	US-PGPUB; USPAT; EPO; JPO; DERWENT	AND	ON	2008/08/06 09:14
S25	4	solder NEAR (particle OR precipitate) AND (micron OR micrometer OR um) AND flux NEAR ((organic ADJ acid) OR (free ADJ fatty ADJ acid) OR (fatty ADJ acid ADJ ester) OR (neopentylpolyol ADJ ester))	US-PGPUB; USPAT; EPO; JPO; DERWENT	AND	ON	2008/08/06 09:18
S26	1	(reaction ADJ temperature) solder NEAR (particle OR precipitate) AND (micron OR micrometer OR um) AND flux NEAR ((organic ADJ acid) OR (free ADJ fatty ADJ acid) OR (fatty ADJ acid ADJ ester) OR (neopentylpolyol ADJ ester))	US-PGPUB; USPAT; EPO; JPO; DERWENT	AND	ON	2008/08/06 13:04
S27	3	(reaction ADJ temperature) solder NEAR (particle OR precipitate) AND flux NEAR ((organic ADJ acid) OR (free ADJ fatty ADJ acid) OR (fatty ADJ acid ADJ ester) OR (neopentylpolyol ADJ ester))	US-PGPUB; USPAT; EPO; JPO; DERWENT	AND	ON	2008/08/06 13:05
S28	3	2004/0250919 AND melting	US-PGPUB; USPAT; EPO; JPO;	AND	ON	2008/08/06 14:02

			DERWENT			
S29	162	neopentyl polyol ester	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2008/08/06 16:59
S30	34835	acid value	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2008/08/06 17:05
S31	2	"6742701" AND flux AND ratio	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/08/06 17:37
S32	2	"20030214795" AND ratio	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/08/06 17:39
S33	2	"20030047034" AND ratio	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/08/06 17:40
S34	1	"20030047034" AND ratio AND (sn OR tin)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/08/06 17:41
S35	1	"20040250919" AND reflow	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/08/06 18:08
S36	1	"20040250919" AND acid ADJ value	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/08/07 11:25
S54	250	solder particle NEAR "30"	US-PGPUB; USPAT; USCOR; EPO; JPO; DERWENT	AND	ON	2009/12/14 11:12
S55	29	bump solder fine particle NEAR "30"	US-PGPUB; USPAT; USCOR; EPO; JPO; DERWENT	AND	ON	2009/12/14 11:13
S56	6	("2004/0250919").URPN.	USPAT	AND	ON	2011/12/15 18:28
S57	0	solder neopentylpolyolester acid	USPAT	AND	ON	2011/12/15 18:29
S58	0	solder neopentylpolyolester	USPAT	AND	ON	2011/12/15 18:30
S59	3	neopentylpolyolester	USPAT	AND	ON	2011/12/15 18:30
S60	1	neo\$pentyl\$poly\$ol\$ester	USPAT	AND	ON	2011/12/16 15:02
S61	344	neopentyl NEAR5 polyol NEAR5 ester	USPAT	AND	ON	2011/12/16 15:04
S62	4	neopentyl NEAR5 polyol NEAR5 ester solder	USPAT	AND	ON	2011/12/16 15:04

S63	415	neopentyl NEAR5 polyol NEAR5 ester OR neopentylpolyol NEAR5 ester OR neopentyl NEAR5 polyolester OR neopentylpolyolester	USPAT	AND	ON	2011/12/16 15:07
S67	24	(neopentyl NEAR5 polyol NEAR5 ester OR neopentylpolyol NEAR5 ester OR neopentyl NEAR5 polyolester OR neopentylpolyolester) flux	USPAT	AND	ON	2011/12/16 15:07
S68	5	(neopentyl NEAR5 polyol NEAR5 ester OR neopentylpolyol NEAR5 ester OR neopentyl NEAR5 polyolester OR neopentylpolyolester) flux solder	USPAT	AND	ON	2011/12/16 16:03
S69	6	("2004/0250919").URPN.	USPAT	AND	ON	2011/12/27 16:55
S70	13424	solder bump (flip ADJ chip OR ball ADJ grid ADJ array)	USPAT	AND	ON	2011/12/27 16:57
S71	9429	solder bump (flip ADJ chip OR ball ADJ grid ADJ array) NOT (cream OR paste).detd.	USPAT	AND	ON	2011/12/27 16:58
S72	32	solder bump (flip ADJ chip OR ball ADJ grid ADJ array) NOT (cream OR paste).detd. fatty NEAR5 acid NEAR5 ester	USPAT	AND	ON	2011/12/27 16:58
S74	5	neopentylpolyolester	US-PGPUB; USPAT	OR	ON	2012/02/06 10:38
S75	3	neo\$pentyl\$poly\$ol\$ester	US-PGPUB; USPAT	OR	ON	2012/02/06 10:39
S77	40	neopentyl NEAR5 polyolester	US-PGPUB; USPAT	OR	ON	2012/02/06 10:40
S82	0	solder fatty NEAR5 fatty ADJ acid ADJ ester	US-PGPUB; USPAT	AND	ON	2012/02/06 10:41
S83	5	solder fatty NEAR5 fatty ADJ acid ADJ ester	US-PGPUB; USPAT	AND	ON	2012/02/06 10:42
S84	1	"7576434"	US-PGPUB; USPAT	OR	ON	2012/02/08 13:43
S85	628	solder ADJ paste spin NEAR5 coat\$3 (immers\$5 OR dip\$4)	US-PCPUB; USPAT	AND	ON	2012/02/08 13:47
S86	0	(solder ADJ paste spin NEAR5 coat\$3 (immers\$5 OR dip\$4)).ab.	US-PCPUB; USPAT	AND	ON	2012/02/08 13:47
S87	15	solder ADJ paste.ab. spin NEAR5 coat\$3 (immers\$5 OR dip\$4)	US-PCPUB; USPAT	AND	ON	2012/02/08 13:48
S88	42	solder ADJ paste.ab. solder ADJ paste NEAR5 (spin NEAR5 coat\$3 OR (immers\$5 OR dip\$4))	US-PCPUB; USPAT	AND	ON	2012/02/08 13:56
S89	18	solder ADJ paste.ab. solder ADJ paste NEAR5 (spin NEAR5 coat\$3 OR (immers\$5 OR dip\$4)) bump\$3	US-PCPUB; USPAT	AND	ON	2012/02/08 14:00
S90	18	solder ADJ paste.ab. solder ADJ paste NEAR5 (spin\$4 NEAR5 coat\$3 OR (immers\$5 OR dip\$4)) bump\$3	US-PCPUB; USPAT	AND	ON	2012/02/08 14:03
S91	0	solder ADJ paste.ab. solder ADJ paste NEAR5 (spin\$4 NEAR5 coat\$3) bump\$3	US-PCPUB; USPAT	AND	ON	2012/02/08 14:28
S92	1	solder ADJ paste NEAR5 (spin\$4 NEAR5 coat\$3) bump\$3	US-PCPUB; USPAT	AND	ON	2012/02/08 14:28
S93	92	solder ADJ paste NEAR5 (spin\$4 NEAR5 coat\$3 OR (immers\$5 OR dip\$4))	US-PCPUB; USPAT	AND	ON	2012/02/08 14:33

		bump\$3					
S94	133	solder ADJ paste NEAR10 (spin\$4 NEAR5 coat\$3 OR (immers\$5 OR dip\$4)) bump\$3	US-PGPUB; USPAT	AND	ON	2012/02/08 14:34	
S95	287	solder ADJ paste NEAR10 (spin\$4 NEAR5 coat\$3 OR (immers\$5 OR dip\$4))	US-PGPUB; USPAT	AND	ON	2012/02/08 15:09	
S96	1	solder ADJ paste NEAR10 (spin\$4 NEAR5 coat\$3)	US-PGPUB; USPAT	AND	ON	2012/02/08 15:09	

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